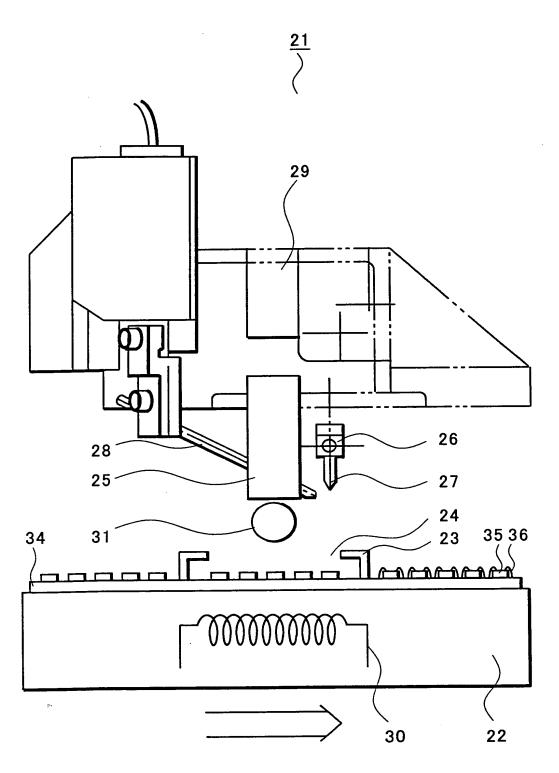
Matter No.: 14225-009002 Page 1 of 12
Applicant(s): Kouji Seki et al.
RECOGNITION DEVICE, BONDING DEVICE, AND METHOD
OF MANUFACTURING A CIRCUIT DEVICE

1/12

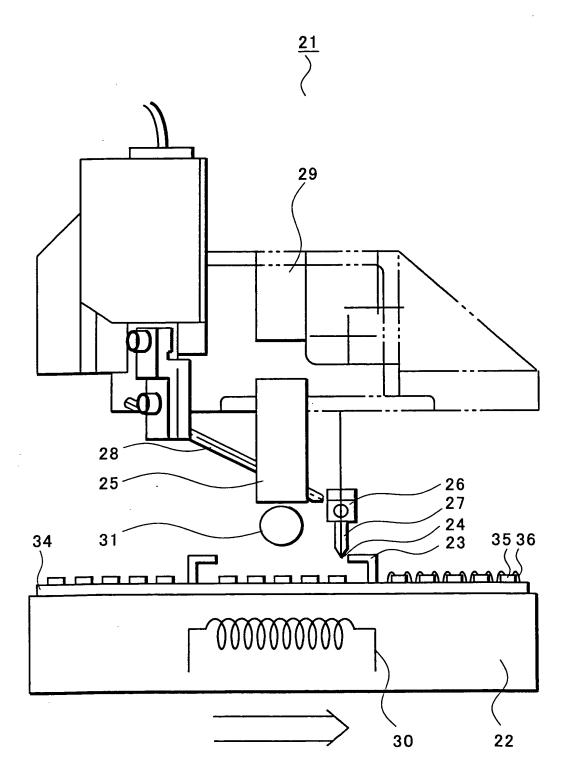
Jection 10019)





Matter No.: 14225-009002 Page 2 of 12 Applicant(s): Kouji Seki et al. RECOGNITION DEVICE, BONDING DEVICE, AND METHOD OF MANUFACTURING A CIRCUIT DEVICE

FIG.2



Matter No.: 14225-009002 Page 3 of 12
Applicant(s): Kouji Seki et al.
RECOGNITION DEVICE, BONDING DEVICE, AND METHOD
OF MANUFACTURING A CIRCUIT DEVICE

FIG.3

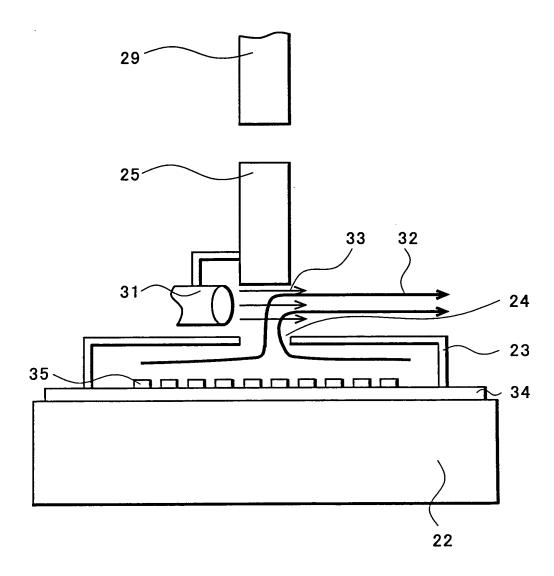


FIG.4A

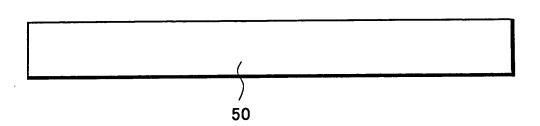


FIG.4B

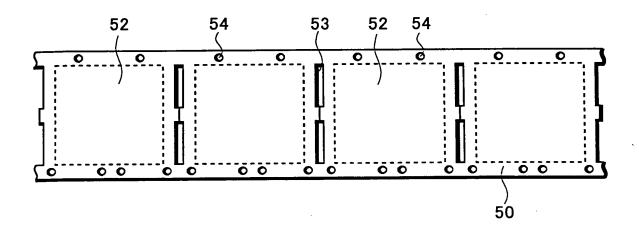
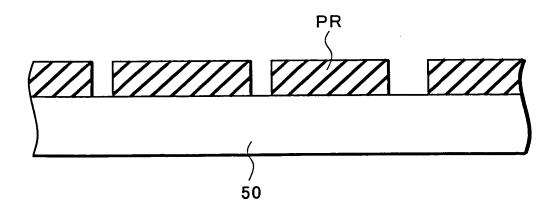


FIG.5



Matter No.: 14225-009002 Page 5 of 12 Applicant(s): Kouji Seki et al. RECOGNITION DEVICE, BONDING DEVICE, AND METHOD OF MANUFACTURING A CIRCUIT DEVICE

FIG.6A

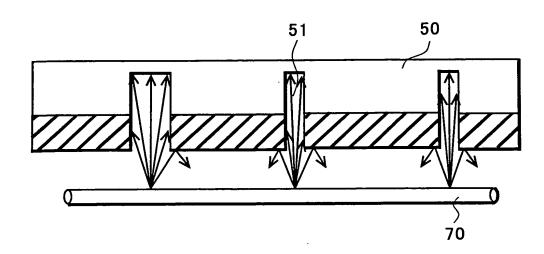
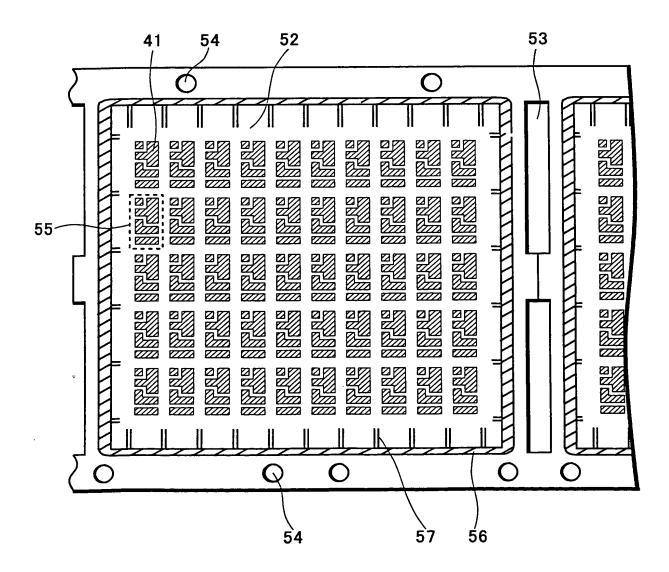


FIG.6B



Page 6 of 12

Matter No.: 14225-009002 Page 6 of 12 Applicant(s): Kouji Seki et al. RECOGNITION DEVICE, BONDING DEVICE, AND METHOD

OF MANUFACTURING A CIRCUIT DEVICE

FIG.7A

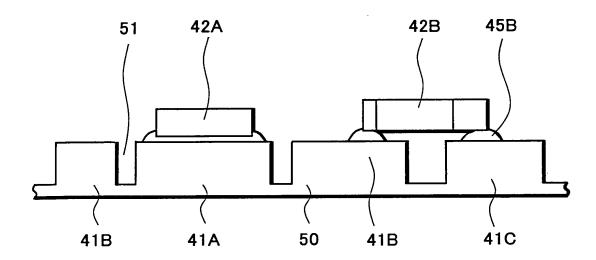
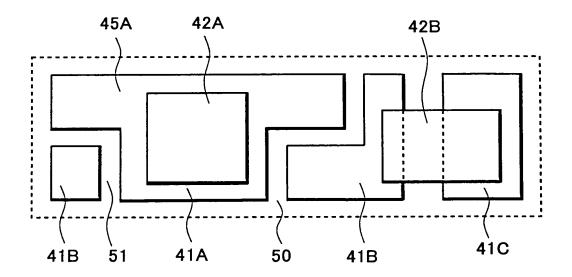


FIG.7B



Matter No.: 14225-009002 Page 7 of 12
Applicant(s): Kouji Seki et al.
RECOGNITION DEVICE, BONDING DEVICE, AND METHOD
OF MANUFACTURING A CIRCUIT DEVICE

FIG.8A

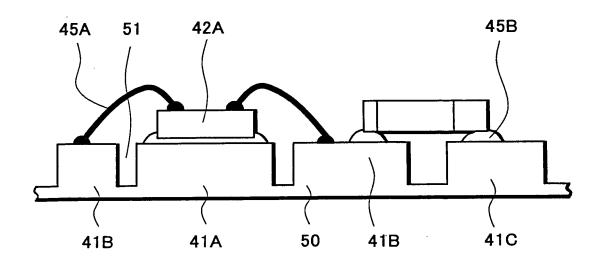
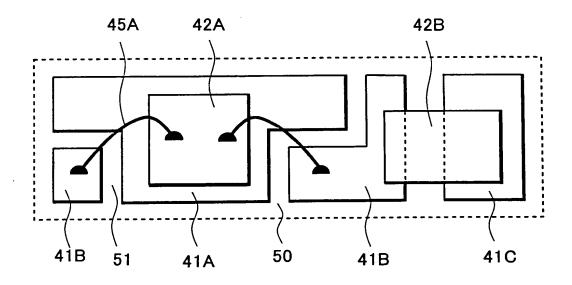


FIG.8B



Matter No.: 14225-009002 Page 8 of 12
Applicant(s): Kouji Seki et al.
RECOGNITION DEVICE, BONDING DEVICE, AND METHOD
OF MANUFACTURING A CIRCUIT DEVICE

FIG.9A

8/12

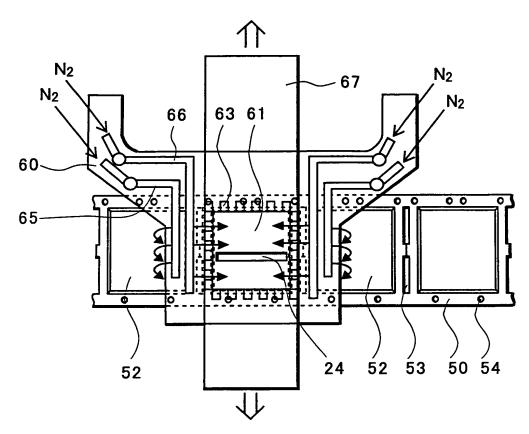
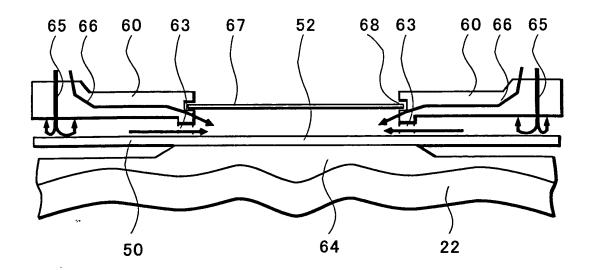


FIG.9B



Matter No.: 14225-009002 Page 9 of 12 Applicant(s): Kouji Seki et al. RECOGNITION DEVICE, BONDING DEVICE, AND METHOD

OF MANUFACTURING A CIRCUIT DEVICE

FIG.10A

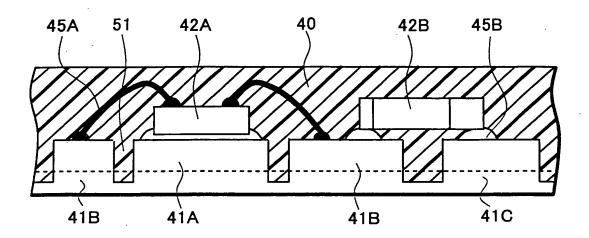
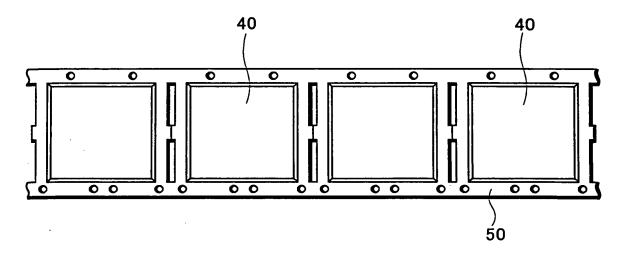


FIG.10B



RECOGNITION DEVICE, BONDING DEVICE, AND METHOD OF MANUFACTURING A CIRCUIT DEVICE

FIG.11

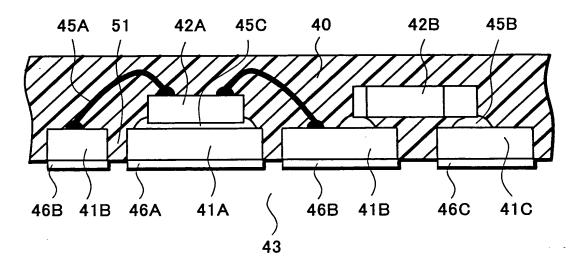
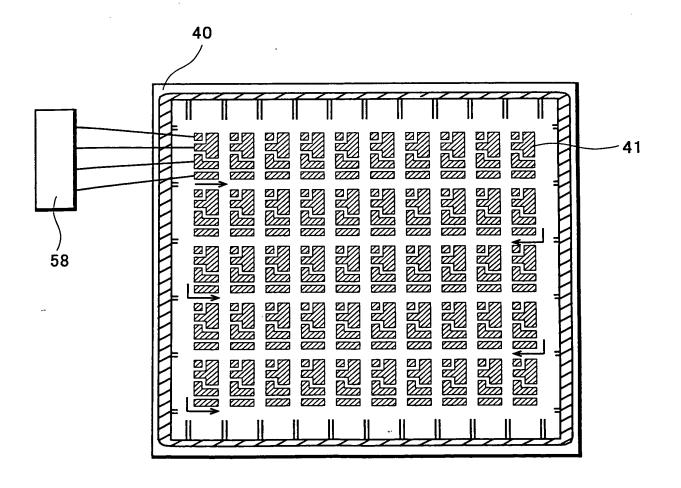


FIG.12



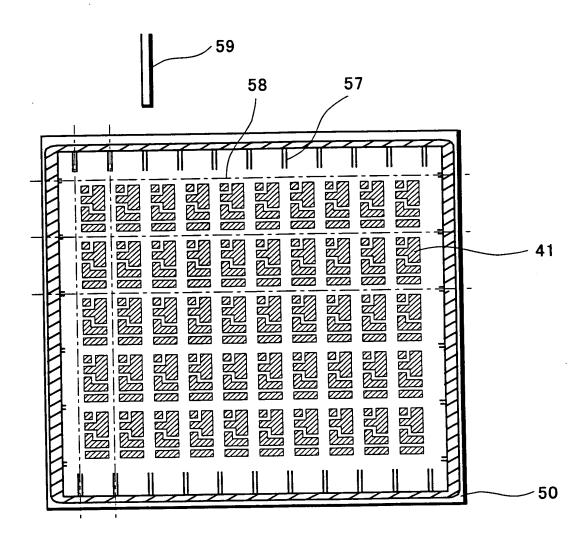
Page 11 of 12

Matter No.: 14225-009002 Applicant(s): Kouji Seki et al.

RECOGNITION DEVICE, BONDING DEVICE, AND METHOD

OF MANUFACTURING A CIRCUIT DEVICE

FIG.13



Page 12 of 12

Matter No.: 14225-009002 Page 12 of 12 Applicant(s): Kouji Seki et al. RECOGNITION DEVICE, BONDING DEVICE, AND METHOD OF MANUFACTURING A CIRCUIT DEVICE

12/12

FIG.14

